

**Amendments to the Specification:**

On page 1, please insert the following section after the Title and before the Background of the Invention section:

**RELATED APPLICATION**

The present application is a divisional of U.S. Application Serial No. 10/152,945 entitled SEMICONDUCTOR PACKAGE AND METHOD OF MAKING LEADFRAME HAVING LEAD LOCKS TO SECURE LEADS TO ENCAPSULANT filed May 22, 2002, which is a divisional of U.S. Application Serial No. 09/444,035 entitled SEMICONDUCTOR PACKAGE AND METHOD OF MAKING LEADFRAME HAVING LEAD LOCKS TO SECURE LEADS TO ENCAPSULANT filed November 19, 1999 and issued as U.S. Patent No. 6,448,633 on September 10, 2002.